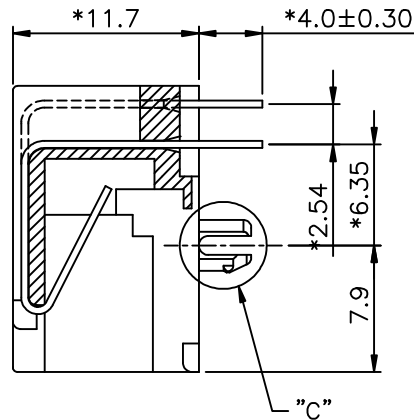
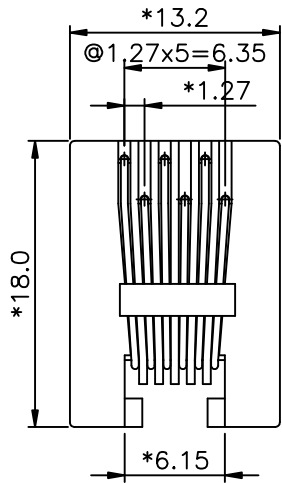
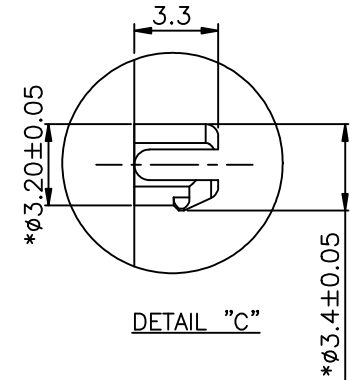
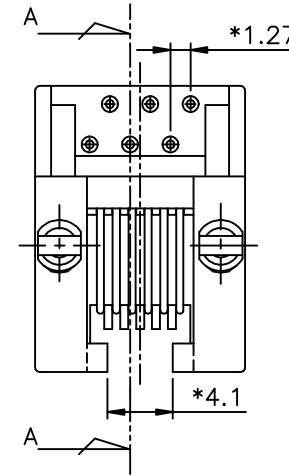


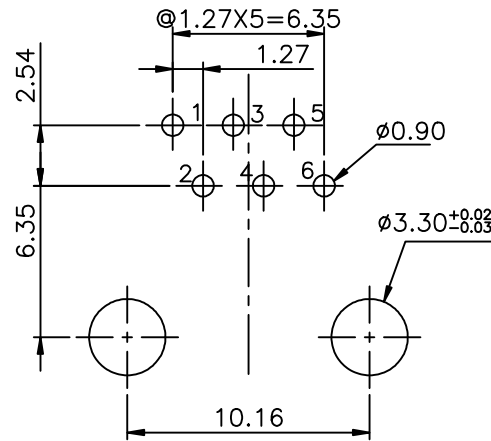
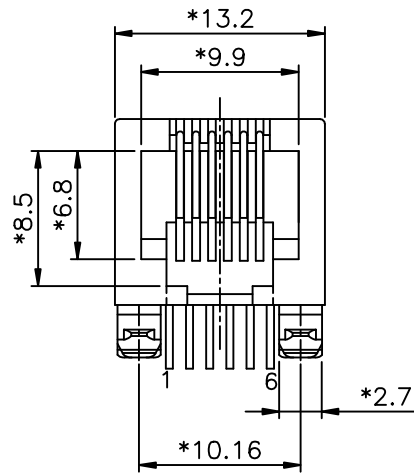
REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
▲		ADD P/N.	08/09/05	



SECTION A-A



DETAIL "C"



PC Board Layout  
Component Side Shown

**NOTES:**

**ELECTRICAL:**

- VOLTAGE RATING : 125 VAC RMS.
- CURRENT RATING : 1.5 AMP.
- CONTACT RESISTANCE : 30 MILLIOHMS MAX.
- INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 1000 VDC.
- DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

**MECHANICAL:**

- HOUSING MATERIAL : FR52 UL94V-0.
- CONTACT MATERIAL : PHOSPHOR BRONZE  $\phi$ 0.46mm.
- PLATING : GOLD PLATING OVER NICKEL.
- OPERATING LIFE : 750 CYCLES MIN.
- PCB RETENTION PRE-SOLDER : 1 LB MIN.
- PCB RETENTION POST-SOLDER: 10 LBS MIN.

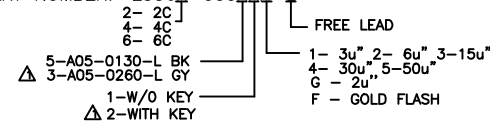
**ENVIRONMENTAL:**

- STORAGE : -40°C TO +85°C.
- OPERATION: -40°C TO +85°C.
- WAVE SOLDERING TEMPERATURE: 255~265°C (5~10 SECONDS)

MATES WITH MODULAR PLUG CONFORMING TO  
FCC PART 68, SUBPART F.

CUL FILE NO. E163191

PART NUMBER: E536X-000XXX-L



DETACHED LISTS	MM (INCH)	DFTO QSJ	DATE 3/11/05	FULL RISE ELECTRONIC CO., LTD	
	TOLERANCES EXCEPT AS NOTED	CHKD	DATE		
	.0 ±0.20	MFO	DATE	TITLE	
	.00 ±0.15	APPLV XLF	DATE 08/13/05	90° VERY L/P PCB JACK 6P	
.000 ±0.075	MATERIAL :		DRAWING NO. GE533077-LA	SIZE A3	REV 1
ANGLES ±	QT'Y :		/PART NO. SEE NOTE		
THIRD ANGLE PROJECTION	FINISH :		DO NOT SCALE DRAWING	SHEET X	OF Y
	SCALE : 2.5:1				